

Please amend the claims as follows. This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claim 1 (currently mended) An apparatus for preparing a wafer, comprising:

a wafer backside plate positioned under a wafer location, the wafer backside plate having a top surface and a back surface, the wafer backside plate including a cylindrical edge lip that defines a central aperture, the cylindrical edge lip including a pin;

a central shaft fitting within the central aperture, the central shaft including a height adjustment slot configured to engage the pin, the pin being capable of sliding within the height adjustment slot~~and engaging the wafer backside plate~~, the wafer backside plate being configured to automatically slide to a second position by centrifugal force when the wafer backside plate and the shaft are spinning during rotational wafer processing and a first position when the wafer backside plate and the shaft stop, the wafer backside plate sliding independent of non-rotational movement of the shaft, and wherein a gap defined between the top surface of the wafer backside plate and the wafer location is less when in the second position than when in the first position.

Claims 2-3 (cancelled)

Claim 4 (currently Amended): An apparatus of claim 3 1, wherein the height adjustment slot includes,
an initial position; and
a last position,

wherein the pin is movably disposed within the height adjustment slot such that the pin slides from the initial position in the height adjustment slot to the last position in the height adjustment slot during rotational wafer processing.

Claim 5 (currently amended): An apparatus of claim 3 1, wherein the height adjustment slot includes,

an initial position; and

a last position,

wherein the pin is movably disposed within the height adjustment slot such that the pin slides from the last position in the height adjustment slot to the initial position in the height adjustment slot when completing rotational wafer processing.

Claims 6-7 (previously cancelled)

Claim 8 (currently amended): An apparatus for preparing a wafer, comprising:

a chuck having a plurality of grippers for holding the wafer;

a wafer backside plate positioned under a wafer location, the wafer backside plate having a top surface and a back surface, the wafer backside plate including a cylindrical edge lip that defines a central aperture, the cylindrical edge lip being defined on the back surface, the cylindrical edge lip including a pin;

a shaft connected to a central portion of the chuck, the shaft including a height adjustment slot, the height adjustment slot configured to receive and engage the pin ~~the shaft receiving and engaging the cylindrical edge lip of the backside plate~~, the wafer backside plate being configured to automatically slide to a second position by centrifugal force when the chuck, the wafer backside plate, and the shaft are spinning during rotational wafer processing and to a first position when the chuck, the wafer backside plate, and the shaft

stop spinning upon completing rotational wafer processing, the backside plate sliding independent of non-rotational movement of the shaft, and wherein a gap defined between the top surface of the wafer backside plate and the wafer location is less when in the second position than when in the first position.

Claim 9-10 (cancelled)

Claim 11 (currently amended): An apparatus of claim 9 8, wherein the height adjustment slot includes,

an initial position; and

a last position,

wherein the pin is movably disposed within the height adjustment slot such that the pin slides from the initial position in the height adjustment slot to the last position in the height adjustment slot during rotational wafer processing.

Claim 12 (currently amended): An apparatus of claim 9 8, wherein the height adjustment slot includes,

an initial position; and

a last position,

wherein the pin is movably disposed within the height adjustment slot such that the pin slides from the last position in the height adjustment slot to the initial position in the height adjustment slot when completing rotational wafer processing.

Claims 13-14 (previously cancelled)

Claim 15 (currently amended): An apparatus for spinning, rinsing and drying a wafer, comprising:

a chuck having a plurality of wafer holders for holding the wafer during the spinning, rinsing and drying;

a wafer backside plate having a disk-like top surface that mirrors the wafer being held by the holders above the wafer backside plate, the wafer backside plate including a cylindrical edge lip at a center, the edge lip having an inner surface and an outer surface, the inner surface of the edge lip defining that defines a central aperture, the outer surface of the edge lip including a pin;

a shaft connected to a central portion of the chuck, the shaft including a height adjustment slot, the shaft configured to receive and engage the pin~~receiving and engaging the inner surface of~~ included in the outer surface of the edge lip of the backside plate, the wafer backside plate being configured to automatically slide to a second position when the chuck, the wafer backside plate, and the shaft are spinning during rotational wafer processing by centrifugal force, and to a first position when the chuck, the wafer backside plate, and the shaft stop, and wherein a gap defined between the top surface of the wafer backside plate and the wafer is less when in the second position than when in the first position.

Claim 16-17 (cancelled)

Claim 18 (currently amended): An apparatus of claim ~~17~~ 15, wherein the height adjustment slot includes,
an initial position; and
a last position,

wherein the pin is movably disposed within the height adjustment slot such that the pin slides from the initial position in the height adjustment slot to the last position in the height adjustment slot during rotational wafer processing.

Claim 19 (currently amended): An apparatus of claim ~~17~~ 15, wherein the height adjustment slot includes,

an initial position; and

a last position,

wherein the pin is movably disposed within the height adjustment slot such that the pin slides from the last position in the height adjustment slot to the initial position in the height adjustment slot when completing rotational wafer processing.

Claims 20-30 (previously cancelled)

Claim 31 (cancelled)

Claims 32 (currently amended): An apparatus for preparing a wafer, comprising:

a chuck having a plurality of wafer holders for holding the wafer during preparation;

a wafer backside plate positioned under a wafer location, the wafer backside plate having a top surface and a back surface, the wafer backside plate including a cylindrical edge lip that defines a central aperture, the cylindrical edge lip including a pin;

a central shaft fitting within the central aperture, the shaft including a height adjustment slot that is configured to engage the pin~~wafer backside plate~~, the pin configured to slide within the height adjustment slot, the wafer backside plate being configured to automatically slide to an up position along the height adjustment slot by centrifugal force

when the wafer backside plate and the shaft are spinning during rotational wafer processing and a down position along the height adjustment slot when the wafer backside plate and the shaft stop spinning, and wherein a gap defined between the top surface of the wafer backside plate and the wafer location is less when in the up position than when in the down position.

Claim 33 (currently amended): An apparatus for preparing a wafer, comprising:

a wafer backside plate positioned under a wafer location, the wafer backside plate having a top surface and a back surface, the wafer backside plate including a cylindrical edge lip that defines a central aperture, the cylindrical edge lip of the wafer backside plate including a pin;

a central shaft fitting within the central aperture, the shaft including a height adjustment slot that is configured to engage the pin, the pin configured to slide within the height adjustment slot, the wafer backside plate being configured to automatically slide to an up position by centrifugal force when the wafer backside plate and the shaft are spinning during rotational wafer processing and a down position when the wafer backside plate and the shaft stop spinning, and wherein a gap defined between the top surface of the wafer backside plate and the wafer location is less when in the up position than when in the down position.